

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	33	((module or housing) and power and control and (base or plate) and (resin or mold or encapsul\$2 or casting) and power adj (device or module) and (board or substrate) and connect\$3).clm.	US-PGPUB; USPAT; USOCR	OR	ON	2009/11/21 14:15
L2	33	((module or housing) and power and control and (base or plate) and (resin or mold or encapsul\$2 or casting) and (board or substrate) and connect\$3 and power adj (device or module)).clm.	US-PGPUB; USPAT; USOCR	OR	ON	2009/11/21 14:16
L3	61	(module or housing) and power and control and (base or plate) and (resin or mold or encapsul\$2 or casting) and (board or substrate) and connect\$3 and power adj (device or module)	EPO; JPO; DERWENT	OR	ON	2009/11/21 14:16
L4	2605	257/787.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2009/11/21 14:17
L5	2685	257/723.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2009/11/21 14:17
L6	1847	257/706.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2009/11/21 14:17
L7	2239	257/712.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2009/11/21 14:17

L8	518	257/E23.119.ccls.	EPO; JPO; DERWENT	OR	ON	2009/11/21 14:18
L9	16	4 and (module or housing) and power and control and (base or plate) and (resin or mold or encapsul\$2 or casting) and (board or substrate) and connect\$3 and power adj (device or module)	US-PGPUB; USPAT; USOCR	OR	ON	2009/11/21 14:18
L10	38	5 and (module or housing) and power and control and (base or plate) and (resin or mold or encapsul\$2 or casting) and (board or substrate) and connect\$3 and power adj (device or module)	US-PGPUB; USPAT; USOCR	OR	ON	2009/11/21 14:19
L11	166	5 and (module or housing) and power and control and (base or plate) and (resin or mold or encapsul\$2 or casting) and (board or substrate) and connect\$3	US-PGPUB; USPAT; USOCR	OR	ON	2009/11/21 14:19
L12	57	6 and (module or housing) and power and control and (base or plate) and (resin or mold or encapsul\$2 or casting) and (board or substrate) and connect\$3 and power adj (device or module)	US-PGPUB; USPAT; USOCR	OR	ON	2009/11/21 14:19

L13	30	7 and (module or housing) and power and control and (base or plate) and (resin or mold or encapsul\$2 or casting) and (board or substrate) and connect\$3 and power adj (device or module)	US-PGPUB; USPAT; USOCR	OR	ON	2009/11/21 14:19
S1	1	"6201696".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 13:56
S2	1	"5940271".PN.	USPAT; USOCR	OR	ON	2009/08/04 13:56
S3	1	"5398160".PN.	USPAT; USOCR	OR	ON	2009/08/04 13:57
S4	1	"5398160".PN.	USPAT; USOCR	OR	ON	2009/08/04 14:05
S5	1	"5386342".PN.	USPAT; USOCR	OR	ON	2009/08/04 14:05
S6	1	"4814943".PN.	USPAT; USOCR	OR	ON	2009/08/04 14:05
S7	2616	257/723.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:05
S8	2561	257/787.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:05
S9	2447	257/784.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:05
S10	1813	257/706.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:05
S11	2186	257/712.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:06
S12	0	S7 and power and control and (substrate or base or plate) and (wire or lead) and (resin or mold or encapsul \$2 or plastic) and power adj (device or module)	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:07

S14	43	S8 and power and control and (substrate or base or plate) and (wire or lead) and (resin or mold or encapsul \$2 or plastic) and power adj (device or module)	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:07
S17	65	S11 and power and control and (substrate or base or plate) and (wire or lead) and (resin or mold or encapsul \$2 or plastic) and power adj (device or module)	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:08
S18	1	S14 and modulus and hardness and (expansion or coeffecient)	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:09
S19	1	"6703707".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:09
S20	1	S8 and thermoplastic and modulus and (shoreA or hardness) and (expansion or coeffecient or CTE) and (KPa or GPa or kPa)	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:14
S21	716	(resin or mold or encapsul\$2) and thermoplastic and modulus and (shoreA or hardness) and (expansion or coeffecient or CTE) and (KPa or GPa or kPa)	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:15
S22	1	S21 and flexural and shoreA	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:15
S23	1	S21 and shoreA	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:16
S24	110	S21 and shore adj A	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:16

S25	62	S21 and flexural and shore adj A	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 14:16
S26	413	S21 and (CTE or coefficient with expansion)	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 15:16
S27	413	S26 and modulus and hardness	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 15:17
S28	413	S26 and modulus and hardness and thermoplastic	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 15:19
S29	429	257/723.ccls.	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/08/04 16:27
S30	1791	257/787.ccls.	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/08/04 16:28
S31	518	257/E23.119.ccls.	EPO; JPO; DERWENT	OR	ON	2009/08/04 16:28
S32	1	((resin or mold or encapsul\$2) and thermoplastic and (shore adj A) and hardness and (insulat\$3 or dielectric) and (substrate or base) and (power or module)).cim.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 16:31
S33	14	knapp.in. near2 wolfgang.in.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 16:33
S34	8	kaser.in. near2 helmut.in.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 16:33
S35	19	S33 or S34	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 16:33
S36	0	S19 and (resin or mold or encapsul \$2) and thermoplastic and (shore adj A) and hardness and (insulat\$3 or dielectric) and (substrate or base) and (power or module)	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/04 16:34
S37	2616	257/723.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/05 16:47

S38	78	S37 and power and control and (substrate or base or plate) and (wire or lead) and (resin or mold or encapsul \$2 or plastic) and power adj (device or module)	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/05 16:47
S39	2561	257/787.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/05 16:50
S40	43	S39 and power and control and (substrate or base or plate) and (wire or lead) and (resin or mold or encapsul \$2 or plastic) and power adj (device or module)	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/05 16:50
S41	2447	257/784.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/05 16:51
S42	25	S41 and power and control and (substrate or base or plate) and (wire or lead) and (resin or mold or encapsul \$2 or plastic) and power adj (device or module)	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/05 16:51
S43	1813	257/706.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/05 16:54
S44	84	S43 and power and control and (substrate or base or plate) and (wire or lead) and (resin or mold or encapsul \$2 or plastic) and power adj (device or module)	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/05 16:54

S45	1	((resin or mold or encapsul\$2 or casting) and thermoplastic and (shore adj A) and hardness and (insulat\$3 or dielectric) and (substrate or base or board) and (power or module)). clm.	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/05 16:58
S46	528	(resin or mold or encapsul\$2) and thermoplastic and (shore adj A) and hardness and (insulat\$3 or dielectric) and (substrate or base) and (power or module) and (expos \$3 or outside)	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/05 17:00
S47	401	S46 and power and control	US-PGPUB; USPAT; USOCR	OR	ON	2009/08/05 17:01

11/21/09 2:50:48 PM

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